

4. How to lock and unlock The actuator rotates around the rotational axis. Lock: Apply load to rotate the actuator by 90 degree after inserting the FPC. XNG XNG Unlock : Slowly flip up the Actuator lock Pick the actuator to lift Push vertical to lock OOK How to lock How to unlock Accuator at the same timing moment.

Opens* Rotation axis Rotation axis XNG Operate near both-ends of the actuator at the same timing moment. (Around 3 PIN from the end) Operate the center of the actuator Operate with a sharp tool Operation to push the actuator into connector XNG XNG XNG Excessive force to housing Operation from FPC insertion opening side Operate at one end of the actuator Force from reverse direction to actuator. Push horizontally to lock EDC-382064-00-00

PART NO. FH69-40S-0.5SH

FORM HC0011-5-8 1 2 3 4 5 6 7 8

| Instructions for PCB layout

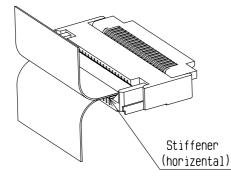
Please design a PCB layout not to apply load to connector and FPC.

[Cautions]

- If the FPC has to be curled/bended in your cabling design, please keep enough degree of freedom in your design to keep the FPC tension free. In this regard, the stiffener is parallel to the PCB.
- Do not mount other components underneath the FPC stiffener which may interfere with the connection.
- Please consult with the FPC manufacturer about FPC bending performance and wire breakage strength while making design.
- Keep enough space for the rotation of the actuator during PCB and component layout design.
- Please consult with our sales representative if you are using FPC with different configuration from our recommendation.

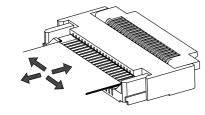






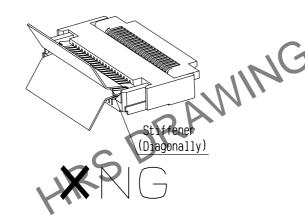


Load applied to FPC

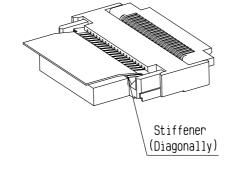




Load applied to stiffener



Housing or parts interfering with the FPC



Instructions for mounting on the PCB

- Refer to recommended layouts for PCB, stencil pattern and FPC dimension.

 Please inspect the size of solder fillet and flux climbing height of the mounted connector while using different land/stencil pattern from our recommendation.
- Please verify your solder resist/silk screening design carefully before implementing the design.
- Apply reflow temperature profile within the specified conditions. For specific applications, the recommended temperature may vary depending on type/volume/thickness of solder paste and size/thickness of PCB.
- Please consult with your solder paste and equipment manufacturer for specific recommendations.
- Please try to minimize the warpage of the PCB. Soldering failure could still occur due to the PCB warpage even if the coplanarity of the connector is under 0.1mm.
- If the connector is mounting on FPC, please make sure to put a stiffener on the backside of the FPC. Recommended stiffner: Glass epoxy material with thickness of 0.3mm MIN.
- Do not apply 0.5N or greater external force on the connector when unreeling or handling the connector before mounting. Excessive mechanical stress may damage the connector before mounting.

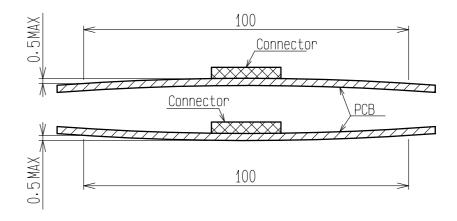
| Instructions for PCB handling after mounting the connector |

The warpage of PCB may apply excessive stress on the connector and damage the connector.

- Splitting a large PCB into several pieces
- ·Installing mounting screw on PCB

During the assembly processes decribed above, care shall be taken so as not to give any stresses of deflection or twisting to the PCB.

-The warpage of a 100mm wide PCB should remain within 0.5mm.



Instructions of hand soldering

- Do not perform hand soldering with the FPC inserted into the connector.
- Do not apply excessive heat. And soldering iron must not touch connector except terminal leads area.
- Do not supply excessive solder (flux).

<INSTRUCTION MANUAL(3)>

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H 75	PART NO.	FH69-40S-0.5SH		
	DRAWING NO.	EDC-382064-00-00		

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[Recommended reflow temperature profile]

The temperatures mentioned above refer to the PCB surface

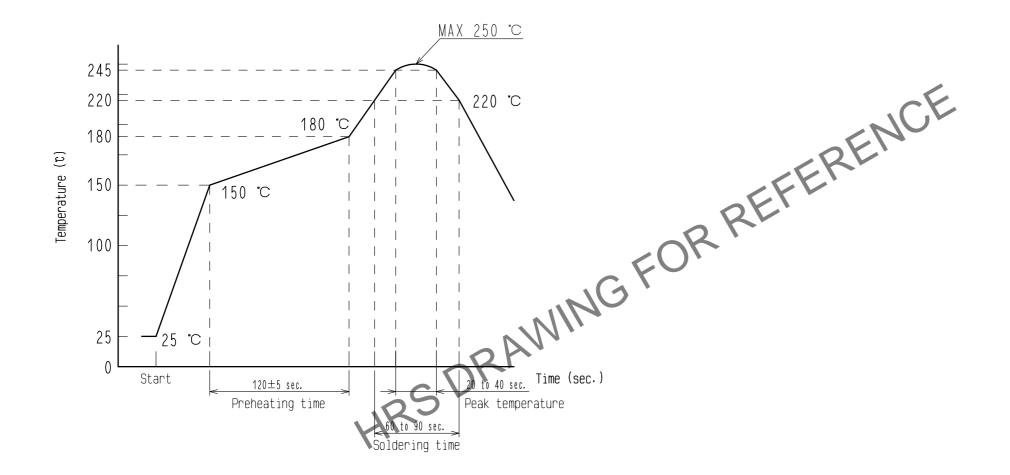
temperature near the connector leads.

For specific applications, the recommended temperature may vary depending on

type/volume/thickness of solder paste and size/thickness of PCB.

Please consult with your solder paste and equipment manufacturer for specific recommendations.

- -Reflow method:IR reflow
- Number of reflow cycles: 2 cycles MAX.



<INSTRUCTION MANUAL(4)>

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